

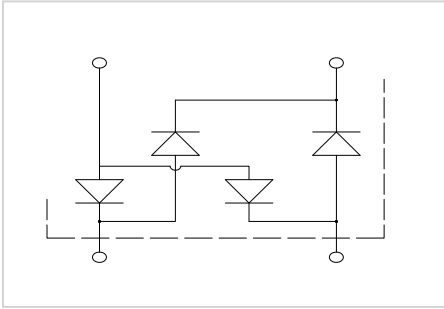
Bridge Rectifiers

Features

- UL recognition, file #E313149
- Ideal for automated placement
- Glass passivated chip junction
- High surge current capability
- Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

Typical Applications

General purpose use in high frequency AC/DC bridge full wave rectification for power supply, lighting ballast, battery charger, home appliances, office equipment, and telecommunication applications.



Mechanical Data

- Package:** MBS
- Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant
- Terminals:** Tin plated leads, solderable per J-STD-002 and JESD22-B102
- Polarity:** As marked on body

Maximum Ratings (T_a=25 °C Unless otherwise specified)

	SYMBOL	UNIT	HMB6S	HMB8S	HMB10S
Device marking code			HMB6S	HMB8S	HMB10S
Maximum DC blocking Voltage	V _{DC}	V	600	800	1000
Average rectified output current @60Hz sine wave, R-load, T _c =115	I _O	A	1.0		
Forward Surge Current (Non-repetitive) @8.3ms Half-sine wave, 1 cycle, T _j =25	I _{FSM}	A	30		
Current squared time @1ms t 8.3ms T _j =25, rating of per diode	I ² t	A ² s	3.7		
Storage temperature	T _{stg}		-55 ~ +150		
Junction temperature	T _j		-55 ~ +150		

Electrical Characteristics T_a=25 °C Unless otherwise specified

	UNIT	TEST CONDITIONS	HMB6S	HMB8S	HMB10S
Maximum reverse recovery time	t _r	I _F =0.5A, I _R =1.0A, I _r =0.25A	75		
Forward voltage drop per diode	V _F	I _F =0.5A	1.7		
Maximum DC reverse current at rated DC blocking voltage per diode	I _R	μA			



HMB6S THRU HMB10S

Thermal Characteristics $T_a=25$ Unless otherwise specified

PARAMETER		SYMBOL	UNIT	HMB6S	HMB8S	HMB10S
Typical Thermal Resistance	Between junction and ambient	R J-A	/W	65.0		
	Between junction and lead	R J-L		28.0		
	Between junction and case	R J-C		20.0		

Note: Device mounted on P.C.B with 35mm*25mm*1.7mm.

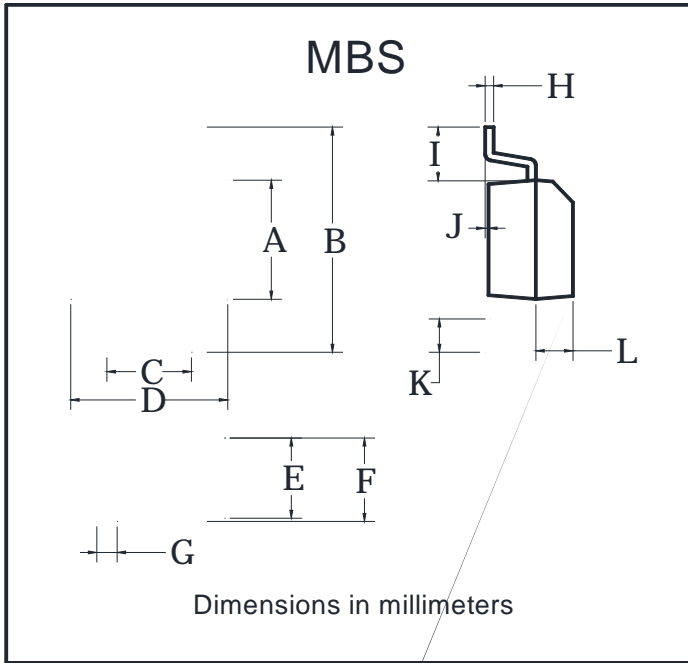
Ordering Information (Example)

PREFERED P/N	PACKING CODE	UNIT WEIGHT(g)	MINIIMUM PACKAGE(pcs)	INNER BOX QUANTITY(pcs)	OUTER CARTON
--------------	--------------	----------------	-----------------------	-------------------------	--------------



HMB6S THRU HMB10S

Outline Dimensions



MBS		
Dim	Min	Max
A	3.60	4.00
B	7.00 Max	
C	2.20	2.60
D	4.50	4.90
E	2.30	2.70
F	3.00 Max	
G	0.56	0.84
H	0.15	0.35
I	1.10	2.12
J	0.20 Max	
K	0.70	1.10
L	0.95	1.53

Suggested pad layout

Dim	Min
P1	6.00
P2	2.40
Q1	1.84
Q2	1.20



HMB6S THRU HMB10S

Disclaimer

The information presented in this document is for reference only. Yangzhou Yangjie Electronic Technology Co., Ltd. reserves the right to make changes without notice for the specification of the products displayed herein to improve reliability, function or design or otherwise.

The product listed herein is designed to be used with ordinary electronic equipment or devices, and not designed to be used with equipment or devices which require high level of reliability and the malfunction of which would directly endanger human life (such as medical instruments, transportation equipment, aerospace machinery, nuclear-reactor controllers, fuel

Mte